

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Ryoichi IKEZAWA	01/19/2006
Masanobu FUJII	01/19/2006
Shinsuke HAGIWARA	01/19/2006
RECEIVING PARTY DATA	
Name:	HITACHI CHEMICAL CO., LTD.
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State/Country:	JAPAN
Postal Code:	163-0449
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11260463
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Total Attachments: 1 source=030351A Assignment#page1.tif	

OP \$40.00 11260463

PATENT

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U.S. ASSIGNMENT

IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter ASSIGNOR) by
HITACHI CHEMICAL CO., LTD.

(Insert ASSIGNEE'S Name(s) Address(es))

1-1, Nishishinjuku 2-chome, Shinjuku-ku, Tokyo 163-0449 Japan

(hereinafter ASSIGNEE), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest to the invention entitled

(Title of Invention)

ENCAPSULATING EPOXY RESIN MOLDING MATERIAL AND SEMICONDUCTOR DEVICE

(*If the assignment is being filed after the filing of the application, this section must be completed)

for which application for Letters Patent of the United States was executed on even date herewith unless otherwise indicated below:

* filed on September 25, 2001 Serial No. PCT/JP01/08303

(Westerman, Hattori, Daniels & Adrian, LLP is hereby authorized to insert the series code, serial number and/or filing date hereon, when known)

and all Letters Patent of the United States to be obtained therefore on said application or any continuation, divisional, substitute, reissue or reexamination thereof for the full term or terms for which the same may be granted.

The ASSIGNOR agrees to execute all papers necessary in connection with the application and any continuation, divisional, reissue or reexamination applications thereof and also to execute separate assignments in connection with such applications as the ASSIGNEE may deem necessary or expedient.

The ASSIGNOR agrees to execute all papers necessary in connection with any interference, litigation, or other legal proceeding which may be declared concerning this application or any continuation, divisional, reissue or reexamination thereof or Letters Patent or reissue patent issued thereon and to cooperate with the ASSIGNEE in every way possible in obtaining and producing evidence and proceeding with such interference, litigation, or other legal proceeding.

IN WITNESS WHEREOF, the undersigned inventor(s) has (have) affixed his/her/their signature(s).

(Signatures)

<u>Ryoichi Ikezawa</u> (Signature)	<u>Ryoichi IKEZAWA</u> (Type Name)	<u>January 19, 2006</u> (Date)
<u>Masanobu Fujii</u> (Signature)	<u>Masanobu FUJII</u> (Type Name)	<u>January 19, 2006</u> (Date)
<u>Shinsuke Hagihara</u> (Signature)	<u>Shinsuke HAGIWARA</u> (Type Name)	<u>January 19, 2006</u> (Date)
..... (Signature) (Type Name) (Date)
..... (Signature) (Type Name) (Date)
..... (Signature) (Type Name) (Date)

NO LEGALIZATION REQUIRED